EMERGING DISPLAY ISSUE: MAR.12, 2025 TOTAL PAGE: 23 VERSION: 1 CUSTOMER ACCEPTANCE SPECIFICATIONS MODEL NO.: ETEMB043027XDRAL (RoHS) FOR MESSRS:	MINED BY:		FILE NO . CAS-0009824
PPROVED BY: Tung Chang Hu CUSTOMER ACCEPTANCE SPECIFICATIONS MODEL NO.: ETEMB043027XDRAL (RoHS) FOR MESSRS:			
PPROVED BY: Tung Chang Hu CUSTOMER ACCEPTANCE SPECIFICATIONS MODEL NO.: ETEMB043027XDRAL (RoHS) FOR MESSRS:	C.H. Cliu	EMERGING DISPLAY	ISSUE : MAR.12, 2025
CUSTOMER ACCEPTANCE SPECIFICATIONS MODEL NO.: ETEMB043027XDRAL (RoHS) FOR MESSRS:		TECHNOLOGIES CORPORATION	TOTAL PAGE: 23
MODEL NO.: ETEMB043027XDRAL (RoHS) FOR MESSRS:	Yung Chang Hu	12011,0200120000	VERSION: 1
ETEMB043027XDRAL (RoHS) FOR MESSRS:	CUSTOMER	ACCEPTANCE SPEC	CIFICATIONS
DATE: BY:	CUSTOMER'S APPROVA	E T E M B 0 4 3 0 2 7 X D R A (RoHS) MESSRS:	L Dilation.

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- 1. GENERAL SPECIFICATIONS
- 1.1 DATA SHEETS FOR EMBEDDED SYSTEM MCU DRIVER PLEASE REFER TO :

STM32U599

1.2 DATA SHEET FOR CAPACITIVE TOUCH PANEL CONTROLLER/ DRIVER PLEASE REFER TO:

MICROCHIP/mXT336UD

1.3 MATERIAL SAFETY DESCRIPTION

ASSEMBLIES SHALL COMPLY WITH EUROPEAN ROHS REQUIREMENTS, INCLUDING PROHIBITED MATERIALS/COMPONENTS CONTAINING LEAD, MERCURY, CADMIUM, HEXAVALENT CHROMIUM, POLYBROMINATED BIPHENYLS (PBB) AND POLYBROMINATED DIPHENYL ETHERS (PBDE), BIS(2-ETHYLHEXYL) PHTHALATE (DEHP), BUTYL BENZYL PHTHALATE (BBP), DIBUTYL PHTHALATE (DBP), DIISOBUTYL PHTHALATE (DIBP).

- 2. MECHANICAL SPECIFICATIONS
 - 2.1 EMBEDDED SYSTEM MECHANICAL SPECIFICATIONS

(1) DISPLAY SIZE	4.3 inch
(2) NUMBER OF DOTS	. 480(RGB)W * 272H DOTS
(3) MODULE SIZE	125.29W * 84.11H *16.6(MAX.)D mm
(4) VIEWING AREA	95.84W * 54.66H mm
(5) ACTIVE AREA	. 95.04W * 53.86H mm
(6) DOT SIZE	0.066W * 0.198H mm
(7) PIXEL SIZE	0.198W * 0.198H mm
(8) LCD TYPE	TFT, IPS, TRANSMISSIVE,
	NORMALLY BLACK
(9) COLOR	16.7M
(10) VIEWING DIRECTION	SUPER WIDE VIEW
(11) BACKLIGHT	LED , COLOR : WHITE
(12) INTERFACE MODE	FD CAN , RS485 , USB(TYPE C)
(13) WEIGHT	. 150.7g

MODEL NO. VERSION **PAGE** EMERGING DISPLAY TECHNOLOGIES CORPORATION $E\,T\,E\,M\,B\,0\,4\,3\,0\,2\,7\,X\,D\,R\,A\,L$ 2 1 2.2 CAPACITIVE TOUCH PANEL MECHANICAL SPECIFICATIONS (1) TOUCH PANEL SIZE ______4.3 inch (2) OUTER DIMENSION ______ 125.29W * 84.11H mm (3) EFFECTIVE AREA -----95.84W * 54.66H mm (4) ACTIVE AREA ------97.04W * 55.86H mm (6) NUMBER OF TOUCH SENSOR -----20*12 SENSORS Einer eine Donat destribute without authorization. *NOTE: ACCORDING TO IMPLEMENTATION DESIGN

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3. ABSOLUTE MAXIMUM RATINGS

3.1 EMBEDDED SYSTEM ELECTRICAL ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	MIN.	MAX.	UNIT	REMARK
POWER VOLTAGE	VP_IN	-0.3	+40	V	VSS=0
INPUT VOLTAGE	VIN	-0.3	4.0	V	

3.2 ENVIRONMENTAL ABSOLUTE MAXIMUM RATINGS

ITEM	OPERATING		STORAGE		△ • REMARK	
TIEW	MIN.	MAX.	MIN. MAX.		KEWIAKK	
AMBIENT TEMPERATURE	-20°C	70°C	-30°C 80°C		NOTE (1),(2),(3)	
HUMIDITY	NOTI	E (2)	NOTE (2)		WITHOUT	
HOMIDITY	NOTI	2(3)	NOTE(3)		CONDENSATION	
CORROSIVE GAS	NOT ACC	EPTABLE	NOT ACCEPTABLE			

NOTE (1): THE ABSOLUTE MAXIMUM RATINGS OF THIS PRODUCT SHOULD NOT BE EXCEEDED AT ANY TIME. IF THESE RATINGS ARE EXCEEDED, THE PRODUCT'S PERFORMANCE IS NOT GUARANTEED AND THE PRODUCT MAY EXPERIENCE PERMANENT DAMAGE.

NOTE (2) : BACKGROUND COLOR CHANGES SLIGHTLY DEPENDING ON AMBIENT TEMPERATURE THIS PHENOMENON IS REVERSIBLE.

NOTE (3): $Ta \le 60^{\circ}C : 90\%RH MAX (96HRS MAX)$.

Ta > 60°C : ABSOLUTE HUMIDITY MUST BE LOWER THAN THE HUMIDITY OF 90%RH AT 60°C(96HRS MAX).

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4. ELECTRICAL CHARACTERISTICS

4.1 EMBEDDED SYSTEM ELECTRICAL CHARACTERISTICS

 $Ta = 25 \, ^{\circ}C$

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT	REMARK
POWER SUPPLY VOLTAGE	VP_IN		7	12	36	V	VGND=0
DOWED CLIDDLY	I _{VP_IN}	VP_IN=7V		180	216	mA	
POWER SUPPLY CURRENT	Ivp_in	VP_IN=12V		110	132	mA	_
CORRENT	Ivp_in	VP_IN=36V		40	48	mA	
LED LIFE TIME		_	(30K)	_	_	HRS	NOTE (4) NOTE (5)

NOTE (1): VIL/VIH/VOL/VOH REFER TO STM32U599 DATA SHEET

NOTE (2): INTERNAL CIRCUIT DIAGRAM OF BACKLIGHT

NOTE (3) : MAXIMUM ALLOWED CURRENT IN LEDS VS. TEMPERATURE ARE AUTOMATICALLY ADJUSTED BY SYSTEM CONTROLLER.

NOTE (4): CONDITIONS; Ta=25 °C, CONTINUOUS LIGHTING

NOTE (5): DEFINITIONS OF FAILURE

LCD LUMINANCE BECOMES HALF OF THE INITIAL VALUE.

5. TIMING CHARACTERISTICS

REFER TO STM32U599 DATA SHEET

6. MCU CHARACTERISTICS

ITEM	MEMO	REMARK	
TIEM	INTERNAL	EXTERNAL	KEWIAKK
SRAM	2.5 MB	√O —	
FLASH	2 MB	32 MB	
EMETO 1106	Do rot distri		

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7. OPTICAL CHARACTERISTICS

7.1 OPTICAL CHARACTERISTICS

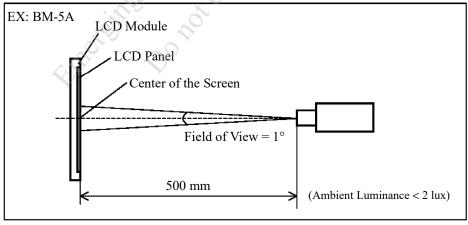
 $Ta=25\pm2^{\circ}C$

ITEM		SYMBOL	COND	ITION	MIN.	TYP.	MAX.	UNIT	REMARK
		θ_{y^+}		θ _x =0°	80	85			
VIEWING ANGLE		$\theta_{ ext{y-}}$	CD> 10	$\Theta_{x}=0$	80	85	_	deg.	NOTE (2) NOTE (3)
VIEWING ANGLE		θ_{x+}	CR≥10	0 -00	80	85	_		
		θ_{x}		$\theta_y=0^\circ$	80	85	_		
CONTRAST RATIO (CENTER))	CR	θx=0°,	θy=0°	800	1000	_ <	1	NOTE (3)
RESPONSE TIME		TR(rise)+ TF(fall)	θx=0°,	θy=0°		30	35	msec	NOTE (4)
	WHITE	Wx			0.25	0.30	0.35		
	WILLE	Uy 0.28 0.3	0.33	0.38					
	DED	Rx			0.54	0.59	0.64	♦.]
COLOR CHROMATICITY	RED	Ry		,	0.27	0.27 0.32	0.37	6,	NOTE (5)
(CENTER)	CDEEN	Gx	θx=0°,	θν=0°	0.30	0.35	0.40		
,	GREEN	Gy	VDD-V		0.54	0.59	0.64		
	BLUE	Bx	// /	SS=12.0V	0.10	0.15	0.20		
BLUE		By	(NTSC	: 50%)	0.06	0.11	0.16	_	
THE BRIGHTNESS OF		D S	00	10.	690	950		a d/ma?	NOTE (6)
MODULE (CENTER)		В	,	0	680	850		cd/m ²	NOTE (6)
THE UNIFORMITY OF					70			%	NOTE (7)
MODULE			70		A.			, ,	1.012(7)

NOTE (1): TEST CONDITION:

AFTER STABILIZING AND LEAVING THE PANEL ALONE AT A GIVEN TEMPERATURE FOR 30 MINUTES. MEASUREMENT SHOULD BE EXECUTED IN A STABLE, WINDLESS, AND DARK ROOM.

THE MEASUREMENT CRITERIA AND CONDITION FOR EITHER BM-5A OR CA-210 OR EQUIVALENT LUMINANCE METER IS BASED ON THE EQUIPMENT'S MANUAL.



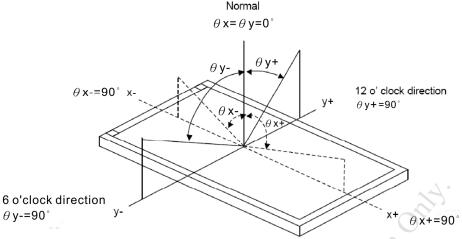
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NOTE (2): DEFINITION OF VIEWING ANGLE:

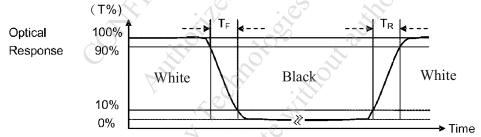


NOTE (3): DEFINITION OF CONTRAST RATIO (CR):

MEASURED AT THE CENTER POINT OF MODULE

BRIGHTNESS MEASURED WHEN LCD IS AT "WHITE STATE" CONTRAST RATIO(CR) = BRIGHTNESS MEASURED WHEN LCD IS AT "BLACK STATE"

NOTE (4): DEFINITION OF RESPONSE TIME: T_R AND T_F THE FIGURE BELOW IS THE OUTPUT SIGNAL OF THE PHOTO DETECTOR.



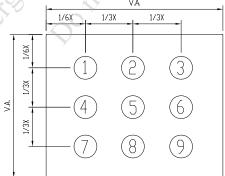
NOTE (5): DEFINITION OF COLOR CHROMATICITY

(a)100% RGB PIXEL DATA TRANSMISSION WHEN ALL THE INPUT TERMINALS OF MODULE ARE ELECTRICALLY POWERED ON.

(b)MEASURED AT THE CENTER POINT OF MODULE

NOTE (6): MEASURED THE BRIGHTNESS OF WHITE STATE AT CENTER POINT.

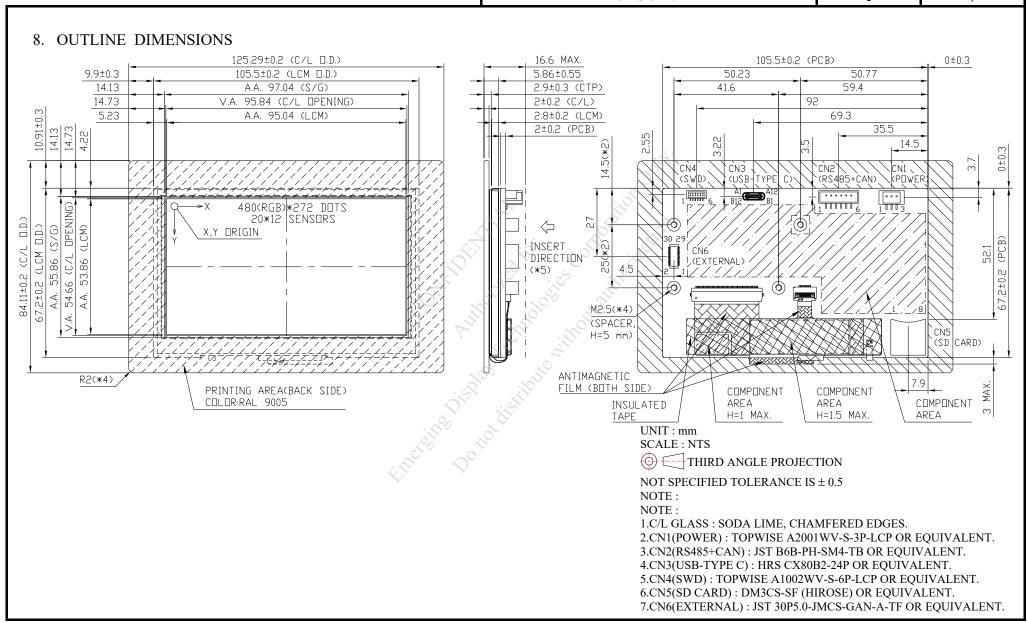
NOTE (7): (a) DEFINITION OF BRIGHTNESS UNIFORMITY



UNIT: mm

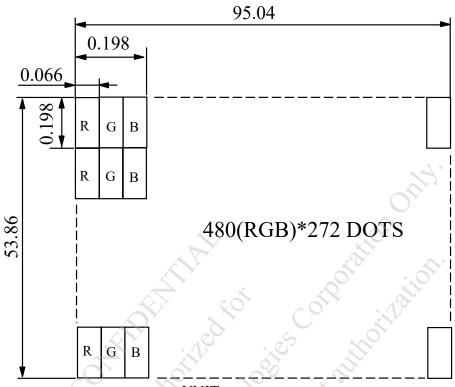
(b) THE BRIGHTNESS UNIFORMITY CALCULATING METHOD

MINIMUM BRIGHTNESS UNIFORMITY: *100% MAXIMUM BRIGHTNESS

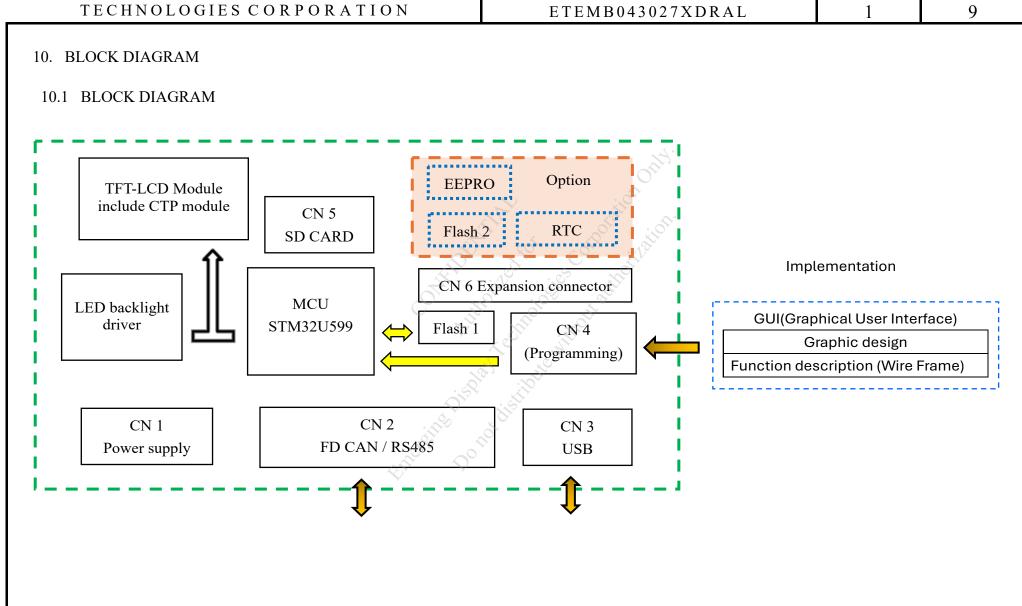


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UNIT : mm
SCALE : NTS
NOT SPECIFIED TOLERANCE IS ± 0.1
DOTS MATRIX TOLERANCE IS ± 0.01



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10.2 IMPLEMENTATION TURN-KEY SOLUTION

BUSINESS MODEL	IMPLEMENTATION	GRAPHIC DESIGN	
MODEL 1	EDT	EDT	
MODEL 2	EDT	CUSTOMER / THIRD PARTY	
MODEL 3	CUSTOMER / THIRD PARTY	CUSTOMER / THIRD PARTY	

NOTE: THE MODEL 3 WILL REQUIRE THE SOFTWARE IMPLEMENTATION BY CUSTOMER OR A THIRD PARTY. CUSTOMER OR THIRD PARTY WILL NEED TO PROVIDE A BIN OR HEX FILE TO EDT DURING INITIAL DESIGN/DEVELOPMENT STAGE OF PROJECT, AND COULD REFERENCE TouchGFX FOR THIS DEVELOPMENT.

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11. INTERFACE SIGNALS

11.1 CN1 POWER SUPPLY INTERFACE

PIN N	Ю.	SYMBOL	FUNCTION		
1		VP_IN	POWER SUPPLY		
2		VP_EN	POWER SUPPLY ENABLE (INTERNAL PULL HIGH)		
3		VSS	GROUND		

11.2 CN2 FD CAN & RS485 INTERFACE

PIN NO.	SYMBOL	FUNCTION		
1	VSS	GROUND		
2	RS485A	RS485-A		
3	RS485B	RS485-B		
4	VSS	GROUND		
5	CANL	LOW LEVEL CAN BUS SIGNAL		
6	CANH	HIGH LEVEL CAN BUS SIGNAL		

11.3 CN3 USB INTERFACE

PIN NO.	SYMBOL	FUNCTION
A1	GND	GROUND
A2	NC	NON CONNECTION
A3	NC	NON CONNECTION
A4	VBUS	POWER SUPPLY
A5	CC1	INTERNAL PULL DOWN RESISTER 5.1K Ohm
A6	D+	D+
A7	D- (D
A8	NC	NON CONNECTION
A9	VBUS	POWER SUPPLY
A10	NC	NON CONNECTION
A11	NC	NON CONNECTION
A12	GND	GROUND
B1	GND	GROUND
B2	NC	NON CONNECTION
В3	NC	NON CONNECTION
B4	VBUS	POWER SUPPLY
B5	CC2	INTERNAL PULL DOWN RESISTER 5.1K Ohm
В6	D+	D+
B7	D-	D-
B8	NC	NON CONNECTION
В9	VBUS	POWER SUPPLY
B10	NC	NON CONNECTION
B11	NC	NON CONNECTION
B12	GND	GROUND

11.4 CN4 PROGRAMMING INTERFACE

PIN NO.	SYMBOL	FUNCTION
1	3V3	POWER SUPPLY (3.3V OUTPUT)
2	SWO	SWO
3	SWDIO	DATA
4	SWCLK	CLOCK
5	NRST	RESET
6	VSS	GROUND

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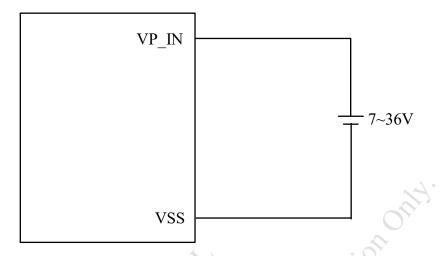
11.5 CN6 EXPANSION CONNECTOR INTERFACE

WE HAVE PROVIDED PCB PADS FOR ONE 30 PIN EXPANSION CONNECTOR, CN6. THE IDEA IS TO MAKE IT POSSIBLE TO ADD FUNCTIONALITY IN A QUICK WAY AND EVENTUALLY ADD THIS TO A REDESIGNED PCB BOARD. WE HAVE ADDED THE MOST OBVIOUS ALTERNATE FUNCTIONS IN THE TABLES. YOU CAN CONSULT THE STM32U599 DATASHEET FOR MORE DETAILS.

PIN		MCU PIN/	ICU PIN/ ALTERNATE FUNCTION						
NO.	SYMBOL	PORT	GPIO	ADC/DAC	SPI	UART	TIMER		
1	5V OUT	_	_		4.				
2	GND	_	_						
3	3V OUT	_	_						
4	GND		_	\sim					
5	EX_I2C3 SCL	PG_7	GPIO			LPUART1_TX			
6	EX_I2C4 SCL	PB_6	GPIO		20, :0,	USART1_TX			
7	EX_I2C3 SDA	PG_8	GPIO	6. 6.		LPUART1_RX			
8	EX_I2C4 SDA	PB_7	GPIO	DY NY C		USART1_RX			
9	EX I2C3 INT	PG 6	GPIO	.180 .69	1100	LPUART1_RTS,			
		_				LPUART1_DE			
10	EX_I2C4 INT	PE_4	GPIO		0		TIM3_CH2		
11	EX_I2C3 RST	PG_5	GPIO) ^v	LPUART1_CTS			
12	EX_I2C4 RST	PE_1	GPIO	Y' CY			TIM17_CH1		
13	EX_SAI2_SCK_A	PG_9	GPIO	DAC1_EXIT9	SPI1 NSS, SPI3_SCK	USART1_TX			
14	EX_SPI2 NSS	PI_0	GPIO				TIM5_CH4		
15	EX_SAI2_FS_A	PG_10	GPIO	3,00	SPI1 SCK, SPI3_MISO	USART1_RX			
16	EX_SPI2 SCK	PI_1	GPIO						
17	EX_SAI2_MCLK_A	PG_11	GPIO	N 15	SPI1 MISO, SPI3_MOSI	USART1_CTS	TIM15_CH2		
18	EX_SPI2 MISO	PI_2	GPIO	. 20			TIM8_CH4		
19	EX_SIA2_SD_A	PG_12	GPIO		SPI1 MISO, SPI3_NSS	USART1_RTS			
20	EX_SPI2 MOSI	PI_3	GPIO	20, 20					
21	EX_USART6 TX	PJ_3	GPIO						
22	EX_USART3 TX	PC_4	GPIO	ADC_IN13, ADC2_IN13, ADC4_IN22					
23	EX_USART6 RX	PJ_4	GPIO						
24	EX_USART3 RX	PC_5	GPIO	ADC1_IN14, ADC2_IN14, TAMPIN4					
25	EX_USART6 RTS	PJ_5	GPIO			UART6_DE			
26	EX_ADC4_IN7	PG_0	GPIO						
27	EX_USART6 CTS	PJ_7	GPIO						
28	EX_DAC_OUT1	PA_4	GPIO	ADC1_IN9					
29	EX_GPIO1	PJ_2	GPIO						
30	EX_GPIO2	PJ_6	GPIO						

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12. POWER SUPPLY



13. CAPACITIVE TOUCH PANEL SPECIFICATION

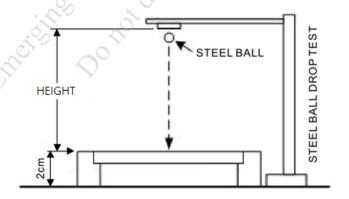
13.1 HARDNESS

ITEM	DESCRIPTION
SURFACE HARDNESS	7H (min)

13.2 DURABILITY

USING STEEL BALL AND FALLING ON TOUCH PANEL SURFACE, FROM THE HEIGHT MUST PASS BELOW CONDITIONS:

ITEM	CONDITION	INSPECTION METHOD	DESCRIPTION
STEEL BALL DROP TEST	WEIGHT: 500g HEIGHT OF FALL: 40 cm (IK7)	VISUAL INSPECTION	SIGN OF FRACTURE OR DAMAGE IS NOT ACCEPTABLE 3 TIMES/ 1 POINTS, 25°C(CENTER TEST)



EMERGING DISPLAY

TECHNOLOGIES CORPORATION

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14. INSPECTION CRITERIA

14.1 APPLICATION

THIS INSPECTION STANDARD IS TO BE APPLIED TO THE LCD MODULE DELIVERED FROM EMERGING DISPLAY TECHNOLOGIES CORP.(E.D.T) TO CUSTOMERS

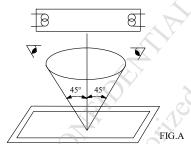
14.2 INSPECTION CONDITIONS

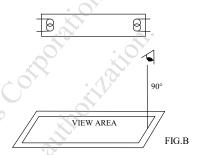
14.2.1 (1)OBSERVATION DISTANCE: 45±5cm

(2) VIEWING ANGLE: ±45°

 $\pm 45^{\circ}$ (FOR SECTION WITHIN VIEWING AREA), REFER TO FIG.A 90° (FOR SECTION OUTSIDE OF VIEWING AREA), REF TO FIG.B PERPENDICULAR TO MODULE SURFACE

VIEWING ANGLE SHOULD BE SMALLER THAN 45°





THE INSPECTION CRITERIA IS ACCORDING TO LINE OF SIGHT. INSPECTION SHALL BE MADE WITHIN THE HALF SECTION OF THE VIEWING CONE GENERATED BY LINE SEGMENT OF 45° WITH RESPECT TO THE VERTICAL AXIS FROM CENTER VERTEX OF LCD, THE FLUORESCENT LAMP AND THE CONE AXIS MUST BE PERPENDICULAR TO THE LCD SURFACE.

IF THE DEFECTS ARE OUTSIDE OF VIEWING AREA, IT SHALL BE INSPECTED BY 90° WITH RESPECT TO THE VERTICAL AXIS FROM EDGE OF VIEWING AREA.

14.2.2 ENVIRONMENT CONDITIONS:

AMBIE	NT TEMPERATURE	25±5°C
AMB	SIENT HUMIDITY	$65 \pm 20\%$ RH
AMBIENT	COSMETIC INSPECTION	600~800 lux
ILLUMINATION	FUNCTIONAL INSPECTION	300~500 lux
INS	SPECTION TIME	10 secs

14.2.3 INSPECTION LOT QUANTITY PER DELIVERY LOT FOR EACH MODEL

14.2.4 INSPECTION METHOD

A SAMPLING INSPECTION SHALL BE MADE ACCORDING TO THE FOLLOWING PROVISIONS TO JUDGE THE ACCEPTABILITY (a)APPLICABLE STANDARD:

ANSI/ ASQ Z1.4 NORMAL INSPECTION LEVEL II

(b)AQL: MAJOR DEFECT: AQL 0.65 MINOR DEFECT: AQL 1.0

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14.3 DEFECTS CLASSIFICATION

TYPE OF DEFECT	INSPECTION ITEM	DEFECT FEATURE	AQL
	1.DISPLAY ON	DEFECT TO MISS SPECIFIED DISPLAY FUNCTION, FOR ALL AND SPECIFIED DOTS EX: DISCONNECTION, SHORT CIRCUIT ETC	
MAJOR DEFECT	2.CTP FUNCTION	NO FUNCTIONBROKEN LINEFALSE TOUCH	0.65
	3.BACKLIGHT	NO LIGHTFLICKERING AND OTHER ABNORMAL ILLUMINATION	
	4.DIMENSIONS	• SUBJECT TO INDIVIDUAL ACCEPTANCE SPECIFICATIONS	
	1.DISPLAY ZONE	 BLACK/WHITE SPOT BUBBLES ON POLARIZER NEWTON RING BLACK/WHITE LINE SCRATCH CONTAMINATION LEVER COLOR SPREAD 	
MINOR DEFECT	2.BEZEL ZONE	STAINSSCRATCHESFOREIGN MATTER	1.0
	3.SOLDERING	 INSUFFICIENT SOLDER SOLDERED IN INCORRECT POSITION CONVEX SOLDERING SPOT SOLDER BALLS SOLDER SCRAPS 	
65	4.DISPLAY ON (ALL ON)	• LIGHT LINE	

NO.	ITEM		CRITE	RIA	
1	DISPLAY ON INSPECTION	1.INCORRECT PATTERN 2.MISSING SEGMENT 3.DIM SEGMENT 4.OPERATING VOLTAGE BEYOND SPEC			
2	OVERALL				
2	DIMENSIONS	1.OVERALL DIMENSION BEYOND SPEC			
3	DOT DEFECT	1.INSPECTION PATTERN: AND BLUE SCREENS. 2. ITEMS BRIGHT DOT DARK DOT TOTAL BRIGHT AND D. NOTE: (1)THE DEFINITION OF DOTHE SIZE OF A DEFECT REGARDED AS ONE DEFECT REGARDED AS ONE DEFECT REGARDED AS ONE DEFECT AND	ARK DOTS OT: TIVE DOT OVEFECTIVE DOT AND UNCHAR ECT MUST BI	PERMIS: N N N N TER 1/2 OF V OT. ANGED IN CK PATTE E VISIBLE	SIBLE NO. ≤2 ≤3 ≤4 WHOLE DOT IS SIZE IN WHICH LCD RN. THROUGH 5% ND ZE IN WHICH LCD
4	BUBBLES ON POLARIZER /SURFACE STAINS /DIRT/CF FAIL/SPOT	BUBBLE SHAL APPEARS ON T (2)THE EXTRANI OBSERVED W	SPLAY AREA L BE IGNORI THE OUTSIDE EOUS SUBSTA HEN THE MO ON OF AVER NG.	D 25 ≤ 0.5 D 25 ≤ 0.4 D .1 ≤ 0.3 D FINED AS A. THE DEF ED IF THE DEF ED	ECT OF POLARIZER POLARIZER BUBBLE 'E DISPLAY AREA. EFINED AS IT CAN BE

O.	ITEM			CRITERIA	
		THE FOLLOWING B	LACK/WHITE S	POT ARE WITHIN THE	
		VIEWING AREA. AV	ERAGE DIAME	TER: D (mm)	
		SIZ	E D	PERMISSIBLE NO.	\Box
	BLACK/WHITE	D≤0	0.15	IGNORE	
5	SPOT CIRCULAR	0.15<1	D≤0.3	4	
	TYPE	0.3 <e< td=""><td></td><td>2</td><td></td></e<>		2	
		D>(0	-
		NOTE (1): THE D		EEN DEFECTS	- /
		` ′		IAN 10mm APART.	
		II.		HIN THE VIEWING ARE	EA.
		WIDTH: W (mm), L			
		SIZE V		PERMISSIBLE NO.	
		W≤(IGNORE	
5	SCRATCH	0.05 <w≤0< td=""><td></td><td>3</td><td></td></w≤0<>		3	
		0.08 <w≤< td=""><td></td><td>3</td><td></td></w≤<>		3	
		W>		0	$\neg \cup$
		NOTE (1): THE D		· ·	
		` /		IAN 5mm APART.	3'
		II.		IITE LINE IS WITHIN TH	IE .
		VIEWING AREA. W			
		SIZE		PERMISSIBLE NO.	
	BLACK /	W≤0		IGNORE	
7	WHITE LINE		0.08, L≤8	3	
	LINEAR TYPE /		0.1, L≤5	3	
	FOREIGN FIBER	W>		0 0	
		NOTE (1): THE D			_
	SHOULD BE MORE THAN 5mm APART.				
BUBBLES WITHIN VIEWING AREA.					
		AVERAGE DIAMET			
		SIZ		PERMISSIBLE NO.	コ
	BUBBLE / DENT	D≤		IGNORE	$\neg \mid \text{D} \checkmark$
3	OR OPTICAL	0.2 <e< td=""><td></td><td>3</td><td>\exists</td></e<>		3	\exists
,	BONDING	0.3 <e< td=""><td></td><td>× 2</td><td>\dashv \blacksquare</td></e<>		× 2	\dashv \blacksquare
	DONDING	D>		0	\dashv \mid \mid \mid
		NOTE (1): THE D		•	_
			7	IAN 10mm APART.	
		AVERAGE DIAMETER		IAN IUIIIII APAKI.	
		SIZ:		PERMISSIBLE NO.	-
		D≤0		IGNORE	
		0.1<		3	$\exists \mid D \checkmark$
`	DIN HOLE	0.2<	——————————————————————————————————————	1	
)	PIN HOLE	D>(_	0	$\exists \vdash $
		NOTE (1): THE DIS		DEFECTS	-
		1/ /	D BE MORE THAN		
		NOTE (2): REFILL			
		ICON PI	N HOLE ARE NOT	ALLOWED.	
					Chip of glass
		CODNED	X ≤ 3mm	$\lor Y \le 3 \text{mm} \lor Z \le t$	City of gittes
Λ	CHIPPING	CORNER	(t: 7	THICKNESS)	Y Y
0	CHIFFING	EDCE	X ≤ 6mm	$Y \le 1 \text{mm}, Z \le t$	
		EDGE		THICKNESS)	
					, ** <u>*</u>
1	CRACKED GLASS		N	OT ACCEPTABLE	
1	LINE DEFECT				
		OBVIOUS VERTICAL OR HORIZONTAL LINE DEFECT IS NOT ALLOWED.			

A ON LAY VEN COLOR AD, DRATION EL BARANCE	 TO BE DETERMINED BASED UPON THE LIMITED SAMPLE. BEZEL MAY NOT HAVE RUST, BE DEFORMED OR HAVE FINGER PRINTS STAINS OF OTHER CONTAMINATION. BEZEL MUST COMPLY WITH JOB SPECIFICATIONS. THERE MAY NOT BE MORE THAN 2mm OF SEALANT OUTSIDE THE SEAL AREA ON THE PCB, AND THERE SHOULD BE NO MORE THAN THREE PLACES. NO OXIDATION OR CONTAMINATION PCB TERMINALS. PARTS ON PCB MUST BE THE SAME AS ON THE PRODUCTION CHARACTERISTIC CHART. THERE SHOULD BE NO WRONG PARTS, MISSING PARTS OR EXCESS PARTS. THE JUMPER ON THE PCB SHOULD CONFORM TO THE PRODUCT CHARACTERISTIC CHART. IF SOLDER GETS ON BEZEL TAB PADS, LED PAD, ZEBRA PAD OR SCREW HOLD PAD; MAKE SURE IT IS SMOOTHED DOWN.
AD, DRATION EL	 TO BE DETERMINED BASED UPON THE LIMITED SAMPLE. BEZEL MAY NOT HAVE RUST, BE DEFORMED OR HAVE FINGER PRINTS STAINS OF OTHER CONTAMINATION. BEZEL MUST COMPLY WITH JOB SPECIFICATIONS. THERE MAY NOT BE MORE THAN 2mm OF SEALANT OUTSIDE THE SEAL AREA ON THE PCB, AND THERE SHOULD BE NO MORE THAN THREE PLACES. NO OXIDATION OR CONTAMINATION PCB TERMINALS. PARTS ON PCB MUST BE THE SAME AS ON THE PRODUCTION CHARACTERISTIC CHART. THERE SHOULD BE NO WRONG PARTS, MISSING PARTS OR EXCESS PARTS. THE JUMPER ON THE PCB SHOULD CONFORM TO THE PRODUCT CHARACTERISTIC CHART. IF SOLDER GETS ON BEZEL TAB PADS, LED PAD, ZEBRA PAD OR SCREW HOLD PAD; MAKE SURE IT IS SMOOTHED DOWN.
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EMERGING DISPLAY

TECHNOLOGIES CORPORATION

NO. ITEM	CRITERIA
NO. ITEM 17 SOLDERING	CRITERIA I. NO SOLDERING FOUND ON THE SPECIFIED PLACE 2. INSUFFICIENT SOLDER (a)LSI, IC A POOR WETTING OF SOLDER IS BETWEEN LOWER BEND OR "HEEL" OF LEAD AND PAD SOLDER FILLET (b)CHIP COMPONENT • SOLDER IS LESS THAN 50% OF SIDES AND FRONT FACE WETTING SOLDER FILLET 1/2 • SOLDER WETS 3 SIDES OF TERMINAL, BUT LESS THAN 25% OF SIDES AND FRONT SURFACE AREA ARE COVERED SOLDER 3. PARTS ALIGNMENT (a)LSI, IC LEAD WIDTH IS MORE THAN 50% BEYOND PAD OUTLINE

EMERGING DISPLAY

TECHNOLOGIES CORPORATION

NO.	ITEM	CRITERIA
		(b)CHIP COMPONENT COMPONENT IS OFF CENTER, AND MORE THAN 50% OF THE LEADS IS OFF THE PAD OUTLINE
17	SOLDERING	
		 4. NO UNMELTED SOLDER PASTE MAY BE PRESENT ON THE PCB. 5. NO COLD SOLDER JOINTS, MISSING SOLDER CONNECTIONS, OXIDATION OR ICICLE. 6. NO RESIDUE OR SOLDER BALLS ON PCB. 7. NO SHORT CIRCUITS IN COMPONENTS ON PCB.
18	BACKLIGHT	 NO LIGHT FLICKERING AND OTHER ABNORMAL ILLUMINATION SPOTS OR SCRATCHES THAT APPEAR WHEN LIT MUST BE JUDGED USING LCD SPOT, LINES AND CONTAMINATION STANDARDS. BACKLIGHT DOESN'T LIGHT OR COLOR IS WRONG.
19	GENERAL APPEARANCE	 NO OXIDATION, CONTAMINATION, CURVES OR, BENDS ON INTERFACE PIN (OLB) OF TCP. NO CRACKS ON INTERFACE PIN (OLB) OF TCP. NO CONTAMINATION, SOLDER RESIDUE OR SOLDER BALLS ON PRODUCT. THE IC ON THE TCP MAY NOT BE DAMAGED, CIRCUITS. THE UPPERMOST EDGE OF THE PROTECTIVE STRIP ON THE INTERFACE PIN MUST BE PRESENT OR LOOK AS IF IT CAUSE THE INTERFACE PIN TO SEVER. THE RESIDUAL ROSIN OR TIN OIL OF SOLDERING (COMPONENT OR CHIP COMPONENT) IS NOT BURNED INTO BROWN OR BLACK COLOR. SEALANT ON TOP OF THE ITO CIRCUIT HAS NOT HARDENED. PIN TYPE MUST MATCH TYPE IN SPECIFICATION SHEET. LCD PIN LOOSE OR MISSING PINS. PRODUCT PACKAGING MUST THE SAME AS SPECIFIED ON PACKAGING SPECIFICATION SHEET. PRODUCT DIMENSION AND STRUCTURE MUST CONFORM TO PRODUCT SPECIFICATION SHEET. THE APPEARANCE OF HEAT SEAL SHOULD NOT ADMIT ANY DIRT AND BREAK.

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15. RELIABILITY TEST

15.1 STANDARD SPECIFICATIONS FOR RELIABILITY OF LCD MODULE

NO.	ITEM	DESCRIPTION
1	HIGH TEMPERATURE TEST (OPERATION)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +70°C FOR 240 HRS
2	LOW TEMPERATURE TEST (OPERATION)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -20°C FOR 240 HRS
3	HIGH TEMPERATURE TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT +80°C FOR 240 HRS
4	LOW TEMPERATURE TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT -30°C FOR 240 HRS
5	HIGH TEMPERATURE / HUMIDITY TEST (STORAGE)	THE SAMPLE SHOULD BE ALLOWED TO STAND AT 60°C, 90% RH 240 HRS
6	THERMAL SHOCK TEST (NOT OPERATED)	THE SAMPLE SHOULD BE ALLOWED TO STAND THE FOLLOWING 10 CYCLES OF OPERATION: +80°C -30°C -30°C -30°C 1CYCLE
7	VIBRATION (NOT OPERATED)	11.76 m/s ² (1.2G), 10~100 Hz XYZ DIRECTIONS, 1 HR EACH
8	SHOCK (NOT OPERATED)	490.0 m/s ² (50G), 10 ms XYZ DIRECTIONS, 1 TIME EACH
9	ESD (ELECTROSTATIC DISCHARGE) (NOT OPERATED)	AIR DISCHARGE ± 8KV CONTACT DISCHARGE ± 4KV (ACCORDING TO IEC-61000-4-2)

NOTE (1): THE TEST SAMPLES HAVE RECOVERY TIME FOR 2 HOURS AT ROOM TEMPERATURE BEFORE THE FUNCTION CHECK. IN THE STANDARD CONDITIONS, THERE IS NO DISPLAY FUNCTION NG ISSUE OCCURRED.

NOTE (2): THERE IS NO DISPLAY FUNCTION NG ISSUE OCCURRED, ALL THE COSMETIC SPECIFICATION IS JUDGED BEFORE THE RELIABILITY STRESS.

NOTE (3): THE MODULE SHOULDN'T BE TESTED MORE THAN ONE CONDITION, AND ALL THE TEST CONDITIONS ARE INDEPENDENT.

NOTE (4): TESTING CONDITIONS AND INSPECTION CRITERIA

NO.	ITEM	TEST MODEL	INSPECTION CRITERIA
1	CURRENT CONSUMPTION	REFER TO SPECIFICATION	THE CURRENT CONSUMPTION SHOULD CONFORM TO THE PRODUCT SPECIFICATION.
2	CONTRAST	REFER TO SPECIFICATION	AFTER THE TESTS HAVE BEEN EXECUTED, THE CONTRAST MUST BE LARGER THAN HALF OF ITS INITIAL VALUE PRIOR TO THE TESTS.
3	APPEARANCE	VISUAL INSPECTION	DEFECT FREE

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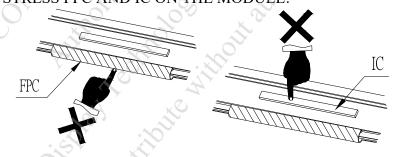
16. CAUTION

16.1 OPERATION

- 16.1.1 DO NOT CONNECT OR DISCONNECT MODULES TO OR FROM THE MAIN SYSTEM WHILE POWER IS BEING SUPPLIED .
- 16.1.2 USE THE MODULE WITHIN SPECIFIED TEMPERATURE; LOWER TEMPERATURE CAUSES THE RETARDATION OF BLINKING SPEED OF THE DISPLAY; HIGHER TEMPERATURE MAKES OVERALL DISPLAY DISCOLOR. WHEN THE TEMPERATURE RETURNS TO NORMALITY, THE DISPLAY WILL OPERATE NORMALLY.
- 16.1.3 ADJUST THE LC DRIVING VOLTAGE TO OBTAIN THE OPTIMUM CONTRAST .
- 16.1.4 POWER ON SEQUENCE INPUT SIGNALS SHOULD NOT BE SUPPLIED TO LCD MODULE BEFORE POWER SUPPLY VOLTAGE IS APPLIED AND REACHES THE SPECIFIED VALUE.

 IF ABOVE SEQUENCE IS NOT FOLLOWED, CMOS LSIS OF LCD MODULES MAY BE DAMAGED DUE TO LATCH UP PROBLEM.
- 16.1.5 NOT ALLOWED TO INFLICT ANY EXTERNAL STRESS AND TO CAUSE ANY MECHANICAL INTERFERENCE ON THE BENDING AREA OF FPC DURING THE TAIL BENDING BACKWARDS!

 DO NOT STRESS FPC AND IC ON THE MODULE!



16.2 STORAGE

- 16.2.1 STORE THE MODULE IN A DARK ROOM OR KEEP IN ORIGINAL PACKAGE WHERE MUST KEEP AT 25±10°C AND 65%RH OR LESS.
- 16.2.2 DO NOT STORE THE MODULE IN SURROUNDINGS CONTAINING ORGANIC SOLVENT OR CORROSIVE GAS.
- 16.2.3 STORE THE MODULE IN AN ANTI-ELECTROSTATIC CONTAINER OR BAG.

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16.3 NOTICE

- 16.3.1 USE A GROUNDED SOLDERING IRON WHEN SOLDERING CONNECTOR I/O TERMINALS . FOR SOLDERING OR REPAIRING, TAKE PRECAUTION AGAINST THE TEMPERATURE OF THE SOLDERING IRON AND THE SOLDERING TIME TO PREVENT PEELING OFF THE THROUGH-HOLE-PAD.
- 16.3.2 DO NOT DISASSEMBLE . EDT SHALL NOT BE HELD RESPONSIBLE IF THE MODULE IS DISASSEMBLED AND UPON THE REASSEMBLY THE MODULE FAILED.
- 16.3.3 DO NOT CHARGE STATIC ELECTRICITY, AS THE CIRCUIT OF THIS MODULE CONTAINS CMOS LSIS. A WORKMAN'S BODY SHOULD ALWAYS BE STATIC-PROTECTED BY USE OF AN ESD STRAP. WORKING CLOTHES FOR SUCH PERSONNEL SHOULD BE OF STATIC-PROTECTED MATERIAL.
- 16.3.4 ALWAYS GROUND THE ELECTRICALLY-POWERED DRIVER BEFORE USING IT TO INSTALL THE LCD MODULE. WHILE CLEANING THE WORK STATION BY VACUUM CLEANER, DO NOT BRING THE SUCKING MOUTH NEAR THE MODULE; STATIC ELECTRICITY OF THE ELECTRICALLY-POWERED DRIVER OR THE VACUUM CLEANER MAY DESTROY THE MODULE.
- 16.3.5 DON'T GIVE EXTERNAL SHOCK.
- 16.3.6 DON'T APPLY EXCESSIVE FORCE ON THE SURFACE.
- 16.3.7 LIQUID IN LCD IS HAZARDOUS SUBSTANCE. MUST NOT LICK AND SWALLOW.
 WHEN THE LIQUID IS ATTACH TO YOUR, SKIN, CLOTH ETC. WASH IT OUT THOROUGHLY AND IMMEDIATELY.
- 16.3.8 DON'T OPERATE IT ABOVE THE ABSOLUTE MAXIMUM RATING.
- 16.3.9 STORAGE IN A CLEAN ENVIRONMENT, FREE FROM DUST, ACTIVE GAS, AND SOLVENT.
- 16.3.10 STORE WITHOUT ANY PHYSICAL LOAD.
- 16.3.11 REWIRING: NO MORE THAN 3 TIMES.